

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: JOSEPH T. LINDGREN *ET AL.*

FILED: CONCURRENTLY HEREWITH

FOR: **MICROELECTRONIC DEVICES WITH  
IMPROVED HEAT DISSIPATION AND  
METHODS FOR COOLING  
MICROELECTRONIC DEVICES**

**Information Disclosure Statement Within Three Months of  
Application Filing or Before First Action – 37 C.F.R. § 1.97(b)**

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

1. Timing of Submission

This information disclosure is being filed within three months of the filing date of this application or date of entry into the national stage of an international application or before the mailing date of a first Office action on the merits, whichever occurs last [37 C.F.R. § 1.97(b)]. The references listed on the enclosed Form PTO-1449 (modified) may be material to the examination of this application; the Examiner is requested to make them of record in the application.

2. Cited Information

☒ Copies of the following references can be found in parent U.S. Application No. 10/228,906, filed August 27, 2002:

☒ All cited references

3. Effect of Information Disclosure Statement (37 C.F.R. § 1.97(h))

This Information Disclosure Statement is not to be construed as a representation that: (i) a search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the cited information is, or is considered to be, material to patentability. In addition, applicant does not admit that any enclosed item of information constitutes prior

art to the subject invention and specifically reserves the right to demonstrate that any such reference is not prior art.

4. Fee Payment

No fees are believed due because this Information Disclosure Statement is being filed before the mailing date of the first Office Action.

However, should the Commissioner determine that fees are due in order for this Information Disclosure Statement to be considered, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 50-0665.

Respectfully submitted,  
Perkins Coie LLP



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Date: Jan 28, 2004

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<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> Form PTO-1449 (Modified) (Use several sheets if necessary)				<b>COMPLETE IF KNOWN</b>	
				Application Number	
				Confirmation Number	
				Filing Date	January 28, 2004
				First Named Inventor	Joseph T. Lindgren
				Group Art Unit	
				Examiner Name	
Sheet	1	of	1	Attorney Docket No.	108298665US1

U.S. PATENT DOCUMENTS						
Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
		6,180,527	B1	Farnworth et al.	01/30/2001	
		6,577,504	B1	Lofland et al.	06/10/2003	
		6,610,560	B2	Pu et al.	08/26/2003	

OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume issue number(s), publisher, city and/or country where published.		
		GARNER, SCOTT D. (Thermacore, Inc.), "Heat pipes for electronics cooling applications," 10 pages, Electronics Cooling Magazine, Vol. 2, No. 3, September 1996, retrieved from the Internet on April 4, 2002, < <a href="http://www.electronics-cooling.com/Resources/EC_Articles/SEP96/sep96_02.htm">http://www.electronics-cooling.com/Resources/EC_Articles/SEP96/sep96_02.htm</a> >.		
		Heat Pipe Technology, Inc., "What Are Heat Pipes?" 2 pages, 1996-2001, retrieved from the Internet on April 4, 2002, < <a href="http://www.heatpipe.com/heatpipes.htm">http://www.heatpipe.com/heatpipes.htm</a> >.		
		Thermacore International, Inc., "Therma-Base™ Heat Sink. Today's Challenge: More Power in Smaller Packages," 2 pages, retrieved from the Internet on April 4, 2002, < <a href="http://www.thermacore.com/thermabase.htm">http://www.thermacore.com/thermabase.htm</a> >.		

EXAMINER	DATE CONSIDERED
*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application(s).	